Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

2SK2229

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain-source ON resistance : $RDS (ON) = 0.12 \Omega (typ.)$ • High forward transfer admittance : $|Y_{fs}| = 5.0 S (typ.)$

• Low leakage current : $IDSS = 100 \mu A \text{ (max) (VDS} = 60 \text{ V)}$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	60	V
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	60	V
Gate-source voltage		V _{GSS}	±20	V
Drain current	DC (Note 1)	I _D	5	Α
Diain current	Pulse (Note 1)	I _{DP}	20	Α
Drain power dissipatio	n	P _D	1.3	W
Single pulse avalanche energy (Note 2)		E _{AS}	129	mJ
Avalanche current		I _{AR}	5	Α
Repetitive avalanche energy (Note 3)		E _{AR}	0.13	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C

Weight: 0.54 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch-a)}	96.1	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 7 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

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Electrical Characteristics (Ta = 25°C)

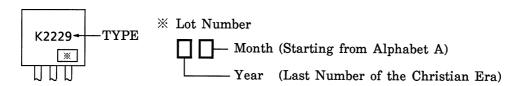
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br voltage	eakdown	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	60	_	_	V
Gate threshold v	/oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance	Б	V _{GS} = 4 V, I _D = 1.3 A	_	0.20	0.30		
	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2.5 A	_	0.12	0.16	Ω	
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	3.0	5.0	_	S
Input capacitano	ce	C _{iss}		_	370	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	60	_	pF
Output capacitance		Coss		_	180	_	
Switching time	Rise time	t _r	$V_{GS} = 10V \qquad I_{D} = 2.5A \qquad V_{OUT}$ $R_{L} = 12\Omega$ $V_{DD} = 30V$ $Duty \leq 1\%, \ t_{W} = 10\mu s$	_	18	_	
	Turn-on time	t _{on}		_	25		ns
	Fall time	t _f		_	55		118
	Turn-off time	t _{off}		_	170		
Total gate charge (Gate-source plus gate-drain)		Qg		_	12	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		8	_	nC
Gate-drain ("miller") charge		Q _{gd}			4	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

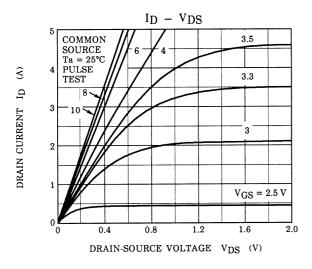
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	20	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} /dt = 50 A/µs	_	70		ns
Reverse recovered charge	Qrr	1DK - 3 Δ, VGS - 0 V, αιDR/αι - 30 Α/μS	_	0.1	_	μC

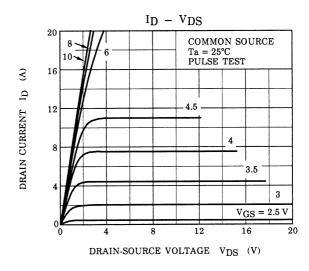
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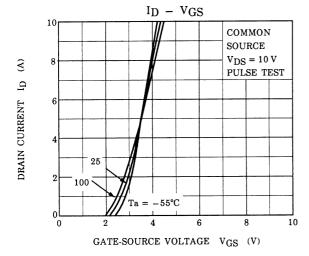
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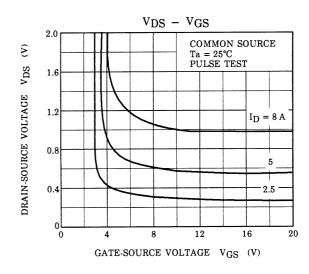


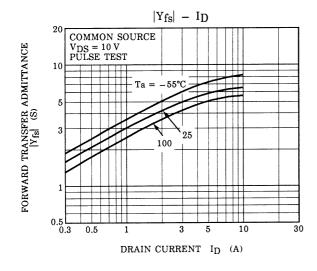
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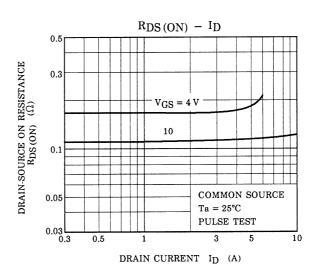




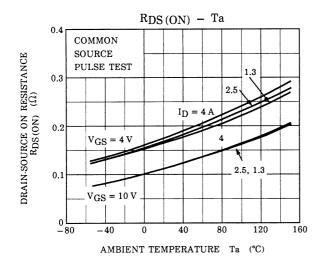


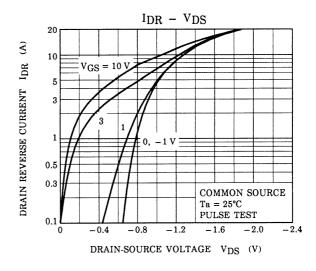


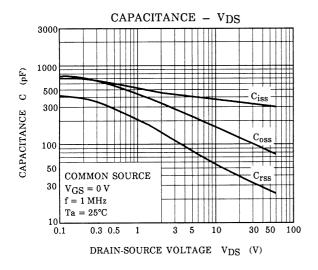


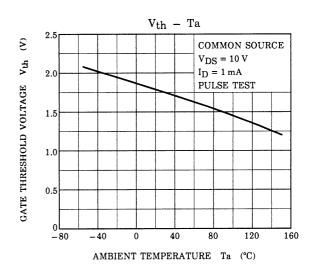


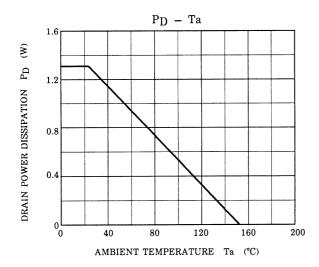
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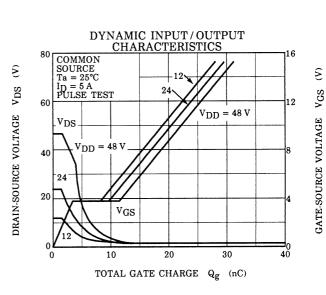




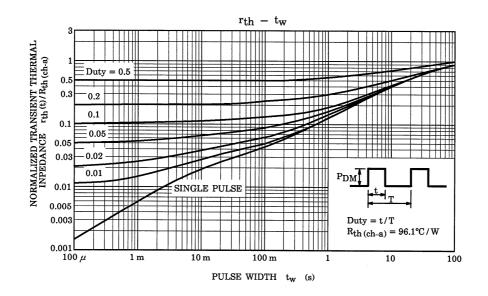


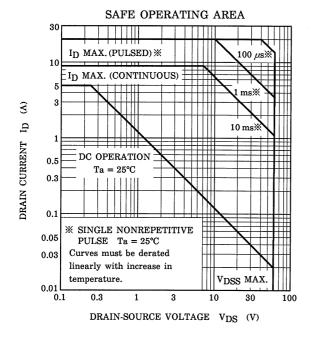


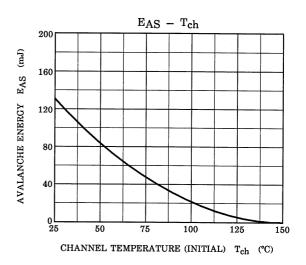


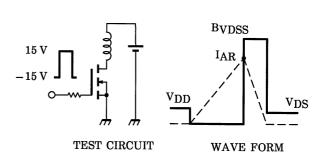


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 25~V,~L = 7~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{Bv_{DSS}}{Bv_{DSS} - V_{DD}} \right) \end{aligned}$$

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